Bond Wire Conversion and Mold Compound Change for ADSP-BF70x/ BF70xW Processors in 184-ball BGA Package

Package Detailed Material Changes

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184-ball BGA Material Changes

ANALOG DEVICES
AHEAD OF WHAT'S POSSIBLE™

Change Item	From	To
Bond Wire Material	Au	CuPdAu
Molding Compound	Sumitomo G770LC	Kyocera KE G1280TS

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